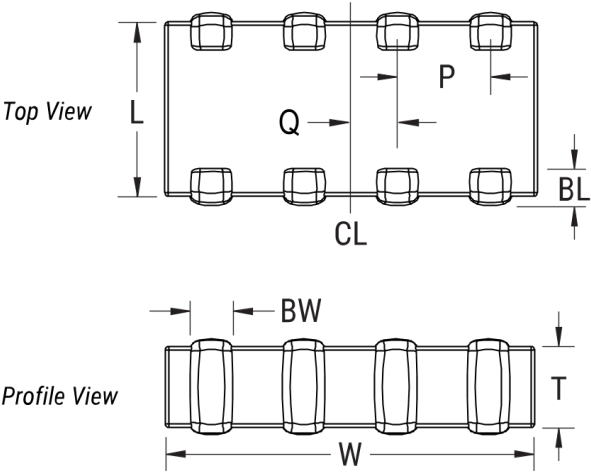




Click [here](#) for the 3D model.

Dimensions	
L	1.6mm +/-0.2mm
W	3.2mm +/-0.2mm
T	0.8mm +/-0.10mm
P	0.8mm +/-0.10mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	Array Comm COG Flex
Style	SMD Array
Description	SMD, MLCC, Array, Flex Termination, Class II
RoHS	Yes
Termination	Flexible Termination
AEC-Q200	No
Typical Component Weight	18 mg
Notes	Last Time Buy Date (LTB): May 30th, 2024.
Chip Size	0612
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	330 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	10 VDC
Dielectric Withstanding Voltage	25 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.